

## KSM26SES8/16MF

16GB 1Rx8 2G x 72-Bit PC4-2666 CL19 260-Pin ECC SODIMM

#### DESCRIPTION

Kingston's KSM26SES8/16MF is a 2G x 72-bit (16GB) DDR4-2666 CL19 SDRAM (Synchronous DRAM) w/ parity, 1Rx8, ECC, memory module, based on nine 2G x 8-bit FBGA components. The SPD is programmed to JEDEC standard latency DDR4-2666 timing of 19-19-19 at 1.2V. Each 260-pin SODIMM uses gold contact fingers. The electrical and mechanical specifications are as follows:

#### **FEATURES**

- Power Supply: VDD = 1.2V
- VDDQ = 1.2V
- VPP = 2.5V
- VDDSPD = 2.20V to 3.60V
- · Functionality and operations comply with the DDR4 SDRAM datasheet
- · 16 internal banks
- Bank Grouping is applied, and CAS to CAS latency (tCCD\_L, tCCD\_S) for the banks in the same or different bank group accesses are available
- Data transfer rates: PC4-2666, PC4-2400, PC4-2133, PC4-1866, PC4-1600
- Bi-Directional Differential Data Strobe
- · 8 bit pre-fetch
- Burst Length (BL) switch on-the-fly BL8 or BC4(Burst Chop)
- · Supports ECC error correction and detection
- On-Die Termination (ODT)
- Temperature sensor with integrated SPD
- · This product is in compliance with the RoHS directive.
- · Per DRAM Addressability is supported
- · Internal Vref DQ level generation is available
- · Write CRC is supported at all speed grades
- · CA parity (Command/Address Parity) mode is supported
- · RoHS Compliant and Halogen-Free

## **SPECIFICATIONS**

| CL(IDD)  | 19 cycles         |  |
|--|-------------------|--|
| Row Cycle Time (tRCmin)                          | 45.75ns(min.)     |  |
| Refresh to Active/Refresh Command Time (tRFCmin) | 350ns(min.)       |  |
| Row Active Time (tRASmin)                        | 32ns(min.)        |  |
| Maximum Operating Power                          | *                 |  |
| UL Rating  | 94 V - 0          |  |
| Operating Temperature                            | 0° C to +85° C    |  |
| Storage Temperature                              | -55° C to +100° C |  |
|  |                   |  |

<sup>\*</sup>See IDD Specifications (page 2)

### **Module Assembly**

**DRAM: MICRON (F-DIE)** 

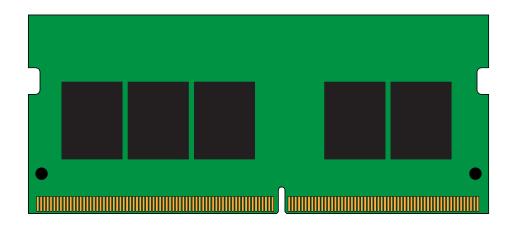
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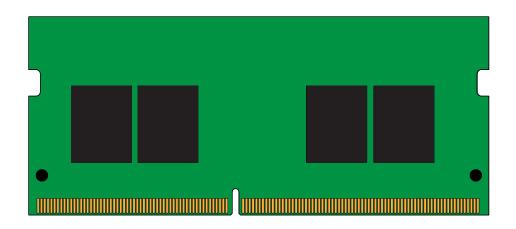
# **IDD Specifications**

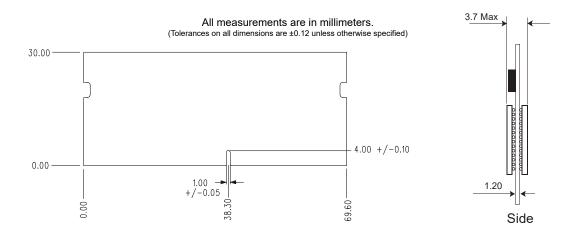
| Symbol                   | 2666 | Units |
|--------------------------|------|-------|
| I <sub>DD0</sub>         | 522  | mA    |
| I <sub>PP0</sub>         | 27   | mA    |
| I <sub>DD1</sub>         | 621  | mA    |
| I <sub>DD2N</sub>        | 387  | mA    |
| I <sub>DD2NT</sub>       | 441  | mA    |
| I <sub>DD2P</sub>        | 342  | mA    |
| I <sub>DD2Q</sub>        | 378  | mA    |
| I <sub>DD3N</sub>        | 531  | mA    |
| I <sub>PP3N</sub>        | 18   | mA    |
| I <sub>DD3P</sub>        | 432  | mA    |
| I <sub>DD4R</sub>        | 1125 | mA    |
| I <sub>DD4W</sub>        | 918  | mA    |
| I <sub>DD5R</sub>        | 612  | mA    |
| I <sub>PP5R</sub>        | 36   | mA    |
| I <sub>DD6N</sub>        | 477  | mA    |
| I <sub>DD6E</sub>        | 810  | mA    |
| I <sub>DD6R</sub>        | 180  | mA    |
| I <sub>DD6A (25°C)</sub> | 99   | mA    |
| I <sub>DD6A (45°C)</sub> | 180  | mA    |
| I <sub>DD6A (75°C)</sub> | 459  | mA    |
| I <sub>DD6A (95°C)</sub> | 810  | mA    |
| I <sub>PP6X</sub>        | 54   | mA    |
| I <sub>DD7</sub>         | 1467 | mA    |
| I <sub>PP7</sub>         | 72   | mA    |
| I <sub>DD8</sub>         | 324  | mA    |

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## **MODULE DIMENSIONS**







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